Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.6 EP)
Lead Count	20
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.22E-02	86.2	862000	38.06	380620
Thermosets	Epoxy resin	Proprietary	1.55E-03	6.0	60000	2.65	26493
Thermosets	Phenol resin	Proprietary	1.55E-03	6.0	60000	2.65	26493
Other inorganic materials	Metal Hydroxide	Proprietary	3.87E-04	1.5	15000	0.66	6623
Other inorganic materials	Carbon black	1333-86-4	7.74E-05	0.3	3000	0.13	1325
Subtotal			2.58E-02	100.00	1000000	44.16	441554

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.73 E-02	97.50	975000	46.72	467226
Copper & its alloys	Iron	7439-89-6	6.58 E-04	2.35	23500	1.13	11261
Copper & its alloys	Zinc	7440-66-6	3.36 E-05	0.12	1200	0.06	575
Copper & its alloys	Phosphorus	7723-14-0	8.40 E-06	0.03	300	0.01	144
Subtotal			2.80 E-02	100.00	1000000	47.92	479206

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.00 E-05	100.0	1000000	0.12	1198

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.30 E-03	100.0	1000000	2.22	22249

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.60 E-04	100.0	1000000	0.27	2738

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.80 E-03	100.0	1000000	4.79	47921

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.33 E-04	77.71	777100	0.40	3990
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	9.33 E-06	3.11	31100	0.02	160
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	9.33 E-06	3.11	31100	0.02	160
Other organic materials	Butyrolactone, gamma-	96-48-0	9.33 E-06	3.11	31100	0.02	160
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	9.33 E-06	3.11	31100	0.02	160
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	9.33 E-06	3.11	31100	0.02	160
Other organic materials	Organosilane	TS ref# 10001	9.33 E-06	3.11	31100	0.02	160
Other inorganic materials	Copper(II) oxide	1317-38-0	9.33 E-06	3.11	31100	0.02	160
Other organic materials	Epoxy resin modifier	TS ref# 10038	1.56 E-06	0.52	5200	0.003	27
Subtotal			3.00 E-04	100.0	1000000	0.51	5134

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.84 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.